Abstracts

Microwave flip chip and BGA technology

J.M. Bedinger. "Microwave flip chip and BGA technology." 2000 MTT-S International Microwave Symposium Digest 00.2 (2000 Vol. II [MWSYM]): 713-716.

Topics discussed in this paper are flip chip and BGA packaging and related assembly issues important in the design of microwave power amplifier and integrated transceiver MMICs. Environmental stress, thermal management, electrical performance, and inspection issues associated with flip chip and ball-grid array packaging will be discussed. The selection of solders, insulating substrates and underfill, will be presented with supporting data for various materials and geometries.

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